

IN THE CLAIMS:

Please amend the claims as follows:

1. (Original) A substrate comprising
a metal plate, and
an insulating film, which is provided on the surface of the metal plate and
which includes needle alumina particles and granular particles.
2. (Original) The substrate of claim 1, wherein the granular particles
include at least one of silica particles, MgO particles, and TiO₂ particles.
3. (Original) The substrate of claim 2, wherein the granular particles
include silica particles.
4. (Currently Amended) The substrate of ~~one of~~ claims 1 to 3, wherein
the needle alumina particles have an aspect ratio of 6 to 15.
5. (Original) The substrate of claim 4, wherein the needle alumina
particles have a major-axis length of 70 nm to 300 nm.
6. (Currently Amended) The substrate of ~~one of~~ claims 1 to 5, wherein
the granular particles have a mean particle size of 5 nm to 80 nm.

7. (Currently Amended) The substrate of ~~one of~~ claims 1 to ~~6~~, wherein the insulating film includes 0.3 mass% to 80 mass% of the needle alumina particles.

8. (Currently Amended) The substrate of ~~one of~~ claims 1 to ~~7~~, wherein the insulating film has a thickness of 0.3 μm to 3.5 μm .

9. (Currently Amended) The substrate of ~~one of~~ claims 1 to ~~8~~, wherein the insulating film has a surface roughness of 0.3 μm or less.

10. (Currently Amended) The substrate of ~~one of~~ claims 1 to ~~9~~, wherein the metal plate is made of Cu, an Fe-Ni-Cr alloy, an Fe-Cr alloy, an Fe-Ni alloy, Fe or Al.

11. (Currently Amended) The substrate of ~~one of~~ claims 1 to ~~10~~, wherein the metal plate has a thickness of 0.05 mm to 0.5 mm.

12. (Currently Amended) A wiring board comprising
the substrate of ~~one of~~ claims 1 to ~~11~~, and
a wiring pattern that has been formed on the surface of the insulating film
on the substrate.

13. (Original) A method of making a substrate, comprising the steps of:
preparing a dispersion solution including needle alumina particles and
granular particles;

applying the dispersion solution onto a metal plate;
drying the metal plate on which the dispersion solution has been applied;
and
baking the metal plate that has been subjected to the step of drying,
thereby forming an insulating film on the surface of the metal plate.

14. (Original) The method of claim 13, wherein the step of applying the dispersion solution is carried out by a coating process.

15. (Currently Amended) The method of claim 13 ~~or~~ 14, wherein the dispersion solution is prepared so as to have a PH of 3.5 to 5.5.

16. (Original) The method of claim 15, wherein the dispersion solution includes at least one of formic acid, acetic acid, salts thereof, and ammonia.

17. (Currently Amended) The method of ~~one of~~ claims 13 ~~to~~ 16, wherein the combined concentration of the needle alumina particles and the granular particles in the dispersion solution is 2 mass% to 6 mass%.

18. (Currently Amended) The method of ~~one of~~ claims 13 ~~to~~ 17, wherein the granular particles include silica particles.

19. (Currently Amended) The method of ~~one of~~ claims 13 to ~~18~~, wherein the needle alumina particles have an aspect ratio of 6 to 15.

20. (Currently Amended) The method of ~~one of~~ claims 13 to ~~19~~, wherein the granular particles have a mean particle size of 5 nm to 80 nm.

21. (Currently Amended) The method of ~~one of~~ claims 13 to ~~20~~, wherein the insulating film includes 0.3 mass% to 80 mass% of the needle alumina particles.